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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Date : 12/15/2004
IN RE APPLICATION OF: TAN, CHONG AIK et al.
APPLN. NO. : 09/736462
FILED : 12/15/2000
FOR : BUMP CHIP LEAD FRAME AND PACKAGE
EXAMINER : Hung V. Ngo
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STATUS INQUIRY

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

S I R :

Applicant(s) respectfully inquire as to the status of the
above-identified patent application. The last communication was:

Issue Fee Paid on June 11, 2004 in response to Notice of Allowance
dated April 22, 2004; Applicants also filed a 312 Amendment and new
Formal Drawings on June 2, 2004.

Please advise us of the current status of this application.

Respectfully submitted,

TAN, CHONG AIK et al.



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FAY 12/15/04

